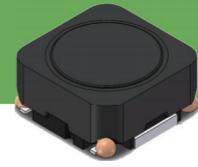


## Assembled SMD Power Inductor –ALPR Series



Operating Temp : -50°C ~+150°C (Including self-heating)

### FEATURES

- ◆ Low loss Realized with low DCR
- ◆ High Performance
- ◆ AEC-Q200 verified

### APPLICATIONS

- ◆ LED Lighting
- ◆ Inverter
- ◆ ECU

### PRODUCT IDENTIFICATION

1	2	3	4	5	6	7
ALPR	1208	S	XXX	M	T	□□□

1	Type
ALPR	车载组装贴片功率电感 Automotive Assembled SMD Power Inductor

2	External Dimensions(L×W×H) [mm]
1208	12.1×12.1×8

3	Feature Type
S	S type

5	Inductance Tolerance
M	±20%

6	Packing
T	Tape & Reel

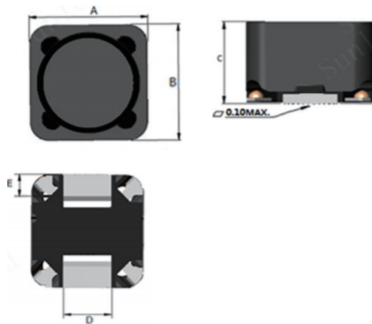
  

7	Design Code
□□□	Standard product is blank

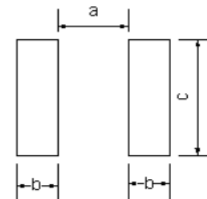
  

4	Nominal Inductance
Example	Nominal Value
4R7	4.7μH
6R8	6.8μH
100	10μH
150	15μH
220	22μH
270	27μH
330	33μH
470	47μH
680	68μH
101	100μH

### SHAPE AND DIMENSIONS



### Recommended Land Pattern



Unit: mm

Series	A	B	C	D	E	a	b	c
ALPR1208S	12.1±0.4	12.1±0.4	8.0±0.3	5.0±0.2	2.4±0.3	6.6ref	3.25ref	5.6ref

**SPECIFICATIONS** ALPR1208S Series

Part Number	Inductance	DC Resistance		Saturation Current		Heat Rating Current	Withstanding Voltage
	100KHz/1V	Max.	Typ.	Max.	Typ.	Typ.	Typ.
Units	μH	mΩ		A		A	V <sub>DC</sub>
Symbol	L	DCR		Isat		I <sub>rms</sub>	/
ALPR1208S4R7MT	4.7±20%	12.5	10.4	11.0	13.0	7.2	500
ALPR1208S6R8MT	6.8±20%	14.0	11.7	9.3	11.0	6.5	
ALPR1208S100MT	10±20%	17.6	14.7	7.6	9.0	5.9	
ALPR1208S150MT	15±20%	21.5	17.9	6.1	7.2	5.2	
ALPR1208S220MT	22±20%	36.6	30.5	5.6	6.6	4.3	
ALPR1208S270MT	27±20%	48.7	40.6	4.7	5.6	3.9	
ALPR1208S330MT	33±20%	54.6	45.5	4.2	5.0	3.6	
ALPR1208S470MT	47±20%	67.0	55.8	3.4	4.0	3.2	
ALPR1208S680MT	68±20%	105.0	87.5	2.8	3.4	2.6	
ALPR1208S101MT	100±20%	148.9	124.1	2.3	2.8	2.2	

Note: ※1:Rated current: Isat(Max) or I<sub>rms</sub>(Typ.), whichever is smaller.

※2:Saturation Current: Typ.Value, DC current at which the inductance drops approximately 30% from its value without current;

※3:Heat Rating Current: DC current that causes an approximate ΔT of 40°C from 20°C ambient.

The part temperature (ambient + temp. rise) should not exceed 150 °C under worst case operating conditions. Circuit design, component placement, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.